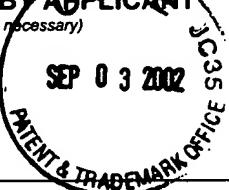


Substitute for form 1449A/PTO <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> (Use as many sheets as necessary)		Complete if Known	
		Application Number	09/259849
		Filing Date	March 1, 1999
		First Named Inventor	Farrar, Paul
		Group Art Unit	2814
		Examiner Name	Peralta, Ginette
Sheet 1 of 1		Attorney Docket No: 00303.557US1	

## US PATENT DOCUMENTS

Examiner Initials*	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate

## FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T <sup>2</sup>

## OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
GP		HIRAO, S., "A Novel Copper Reflow Process Using Dual Wetting Layers", Symposium on VLSI Technology, Digest of Technical Papers, (1997), 57-58	

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